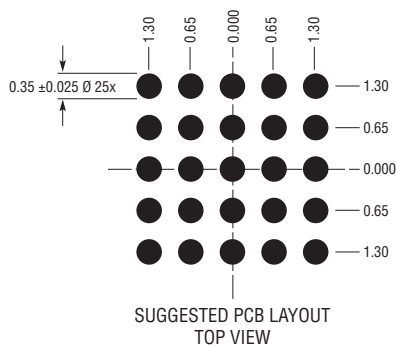
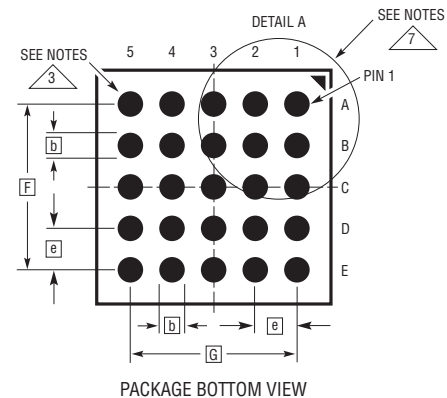
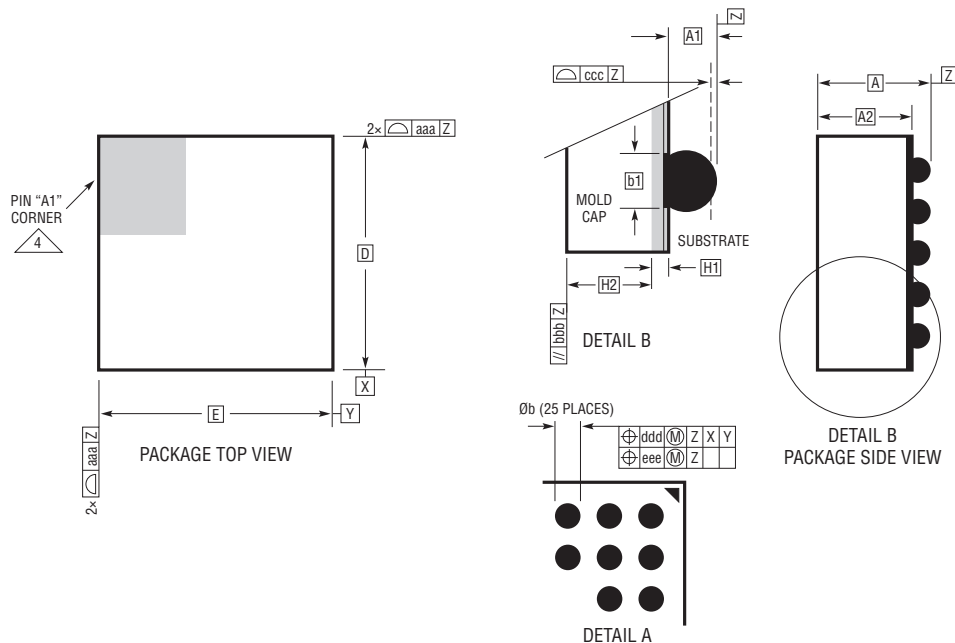


BGA Package
25-Lead (4mm × 4mm × 1.82mm)
 (Reference LTC DWG# 05-08-1566 Rev 0)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	1.66	1.82	1.98	
A1	0.23	0.30	0.37	BALL HT
A2	1.43	1.52	1.61	
b	0.35	0.40	0.45	BALL DIMENSION
b1	0.32	0.35	0.38	PAD DIMENSION
D		4.00		
E		4.00		
e		0.65		
F		2.60		
G		2.60		
H1	0.28	0.32	0.36	SUBSTRATE THK
H2	1.15	1.20	1.25	MOLD CAP HT
aaa			0.15	
bbb			0.20	
ccc			0.10	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF BALLS: 25

- NOTES:**
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 3. BALL DESIGNATION PER JEP95
 4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
7. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

